

Appl. No. 09/886,092
Amdt. dated December 18, 2003
Reply to Office Action of August 19, 2003

Amendments to the Specification:

Please amend the paragraph beginning with the fourth paragraph on page 6 of the Specification according to the following replacement paragraph:

Fig. 13 is a side elevational view of the core substrate assembly of Fig. 12 after a prefabricated, integrated circuit component has been disposed in the cavity; ~~and~~

Please amend the paragraph presented in Amendment "A" for insertion after the fourth paragraph on page 6 of the Specification according to the following two replacement paragraphs:

Fig. 14 is a side elevational view of the core substrate assembly of Fig. 12 after two, prefabricated, integrated circuit components have been disposed in the cavity; and

Fig. 15 is a side elevational view of a core assembly after a cavity has been placed in the exposed upper and lower surfaces.

Please amend the third paragraph on page 7 of the Specification according to the following replacement paragraph:

After the metal layers 14 and 16 have been appropriately patterned to expose substrate surfaces 12a and 12b (as shown in Fig. 2), a prefabricated integrated circuit component 20 may be coupled to substrate surface 12a as shown in Fig. 3, or to both substrate surfaces 12a and 12b as shown in Fig. 11. In ~~another one~~ one embodiment of the present invention ~~one or both of the substrate surfaces surface 12a and 12b~~ may have a cavity, generally illustrated as 24 in Fig. 12. The cavity 24 may be formed by any suitable means, such as by milling, cutting or drilling. ~~The~~ One or more prefabricated, integrated circuit ~~component~~ components 20 (e.g., resistors, capacitors, inductors, etc.) may be conveniently disposed in the cavity 24, as shown in Fig. 13. Alternatively, two prefabricated integrated circuit components may be disposed in the cavity. As shown in FIG. 14, cavity 24 accommodates a first integrated circuit component 20' having pads

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26' and a second integrated circuit component 20'' having pads 26''. Another embodiment of the present invention is shown in Fig. 15 as a side sectional view of core substrate 12 having a cavity 24a in substrate surface 12a and a cavity 24b in substrate surface 12b. Either cavity 24a or 24b may have one or more integrated circuit components. As an example of the present invention, cavity 24a is shown accommodating a first integrated circuit component 20' having pads 26', and cavity 24b is shown accommodating a second integrated circuit component 20'' having pad 26'' and a third integrated circuit component 20''' having pad 26'''.